

## CLAIMS

What is claimed is:

1. A computer assembly comprising:

2. a chassis;

3. a mounting module rigidly coupled to the chassis, the mounting module  
4. for cooling the computer assembly; and

5. at least one circuit board suspended from the module, wherein the at least  
6. one circuit board having a known orientation relative to the module and at least one  
7. circuit board having a variable orientation relative to the chassis.

1. 2. The computer assembly of claim 1 which includes a stabilization support  
2. mechanism for ensuring that the at least one circuit board remains in the known  
3. orientation relative to the module.

1. 3. The computer assembly of claim 1 wherein the mounting module  
2. comprises:

3. a heatsink; and

4. a daughter board coupled to the heatsink, wherein the daughter board  
5. includes a processor.

1. 4. The computer assembly of claim 3 wherein the processor is in contact with  
2. the at least one circuit board.

1. 5. The computer assembly of claim 3 wherein the daughter board is coupled  
2. to the heatsink via a spring-loaded mount.

1           6.     The computer assembly of claim 5 wherein the printed circuit board is  
2     mounted to the chassis via a plurality of standoffs and fasteners at its periphery.

1           7.     The computer assembly of claim 6 wherein the fasteners of the printed  
2     circuit expand longitudinally within apertures in the daughter board to secure the circuit  
3     board to the heatsink assembly.

1           8.     The computer assembly of claim 7 wherein the heatsink assembly is  
2     located relative to the at least one printed circuit board via pin features.

1           9.     A mounting module for a computer assembly comprising:  
2                   a heatsink assembly for cooling the computer assembly, wherein the  
3     heatsink assembly is coupled rigidly to a chassis of the computer assembly and is also  
4     coupled to a printed circuit board within the computer assembly, wherein the printed  
5     circuit board has a known orientation relative to the module and has a variable orientation  
6     relative to the chassis.

1           10.    The mounting module of claim 9 which includes a stabilization support  
2     mechanism for ensuring that the at least one circuit board remains in the known  
3     orientation relative to the module.

1           11.    The mounting module of claim 9 wherein the heatsink assembly  
2     comprises:  
3                   a heatsink; and  
4                   a daughter board coupled to the heatsink, wherein the daughter board  
5     includes a processor.

1           12. The mounting module of claim 11 wherein the processor is in contact with  
2           the at least one circuit board.

1           13. The mounting module of claim 11 wherein the daughter board is coupled  
2           to the heatsink via a spring-loaded mount.